

IN THE CLAIMS

1. (Currently amended) An in-line system used in a semiconductor package assembling process, the system comprising:
a wafer loading unit for loading into the system a wafer having a back side which has not been subjected to grinding;
a wafer grinder for grinding the back side of a wafer loaded by the wafer loading unit;
and
a dicing tape attaching unit constructed and configured to attach a pre-cut dicing tape and a general dicing tape to the back side of the wafer after grinding by the wafer grinder, wherein the dicing tape attaching unit includes a tape loader to supply one of the pre-cut dicing tape and the general dicing tape to the system, and wherein the tape loader rotates in one direction when supplying the pre-cut dicing tape and in the opposite direction when supplying the general dicing tape.
2. (Original) The system of claim 1, wherein a lamination tape is attached to a top side of the wafer, the wafer and attached lamination tape being loaded into the wafer loading unit so as to prevent contamination in the wafer grinder.
3. (Original) The system of claim 1, wherein the wafer grinder includes a UV light radiating portion which irradiates UV light onto a top side of the wafer, so as to effectively remove the lamination tape after the grinding is completed.
4. (Original) The system of claim 1, wherein the wafer after grinding by the wafer grinder has a thickness of 20-200 μm .
5. (Original) The system of claim 1, which further includes a ring frame to which said wafer is attached, and an unloading unit which transfers the ring frame and wafer to a location outside the system.
6. Cancelled
7. Cancelled

8. (Currently amended) The system of claim 1 [[7]], wherein the tape loader rotates clockwise when supplying the pre-cut dicing tape.

9. (Currently amended) The system of claim 1 [[7]], wherein the tape loader rotates counterclockwise when supplying the general dicing tape.

10. (Original) The system of claim 1, which further includes a liner film winding reel which winds the portion of the pre-cut dicing tape remaining after a pre-cut process is performed together with a liner film.

11-21. (Cancelled)